

2007 ASME/CPMT **Interpack Conference** *colocated with the*

**JSME Thermal Engineering & ASME Summer Heat Transfer Conference**  
**Vancouver, BC, Canada** **July 8 – 12, 2007**

We are pleased to bring these two premier conferences co-located in beautiful Vancouver, allowing engineers to expand their technical horizons through participation in both conferences under one roof. We hope you will be able to meet with hundreds of colleagues, exchange ideas and technical information, and learn of the latest technical advances in heat transfer and electronic and photonic packaging disciplines and industries. We have designed the conferences to provide you great value - one registration fee covers both conferences.

Highlights of the conferences include:

- Over 250 papers/12 technical tracks for **Interpack**
- Over 400 papers/18 technical tracks for AJTEC/SHTC

- Learn from experts offering 20 tutorials covering a wide range of topics on Sunday
- Hear insights from leaders in the field during keynote and panel sessions every day
- Over 30 exhibitors showing their latest products
- Socialize with colleagues at welcoming reception and everyday food functions

For only \$100 you can attend any of 20+ tutorials and obtain all the tutorial materials

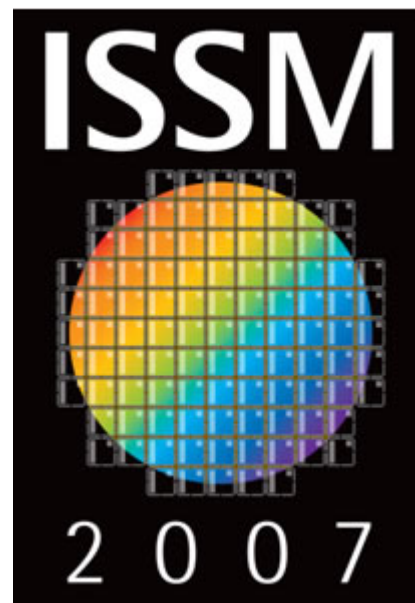
The session schedules for both conferences are posted on the website. Please register today:

[www.interpackconference.org](http://www.interpackconference.org)

## **International Symposium on Semiconductor Manufacturing**

**“Maximizing Operational Efficiencies at the Leading Edge”**

**October 15-17, 2007**  
**Santa Clara, CA, USA**  
**Marriott Hotel**



### **Featured Keynotes:**

**Michael Splinter**, President and Chief Executive Officer  
Applied Materials, Inc

#### **“Optimizing Fab Performance”**

An analysis and vision for the next generation of wafer fabs, highly efficient, lower energy and environmentally sound.

**Nick Bright**, Executive Vice President, Products,  
Lam Research Corporation

#### **“Technology and the Equipment Industry”**

Historically, Moore’s Law has been used as the guiding light for cost and performance in the semiconductor industry. Will this be the case going forward? If not, how will it affect the equipment companies?

Founded in 1992, ISSM is the industry's largest assembly of semiconductor manufacturing professionals dedicated to driving technology innovation and operational excellence within the industry. Currently, ISSM alternates between the US and Japan with the goal of providing an open global forum for the introduction and promotion of new concepts to advance semiconductor manufacturing.

For more information, and to register:

[www.issm.com](http://www.issm.com)